

## AMENDMENTS

### In the Claims:

This listing of claims replaces all prior versions, and listings, of claims in the application:

1. (Previously Presented) A method of manufacturing a semiconductor device, comprising:

    providing a substrate having a first electrode thereon;

    dispensing a sealing resin to a region of the substrate that does not include the first electrode;

    providing a semiconductor chip having a second electrode on a peripheral portion of a front surface of the semiconductor chip;

    placing the semiconductor chip over the substrate so that the front surface of the semiconductor chip faces the sealing resin;

    applying a pressure to a peripheral portion of a back surface of the semiconductor chip so that the first and second electrodes come into a contact; and

    applying, after the application of the pressure to the peripheral portion, a pressure to a central portion of the back surface of the semiconductor chip so that the sealing resin extends in a space between the substrate and the front surface of the semiconductor chip.

2. (Original) The method of claim 1, wherein the sealing resin comprises fillers.

3. (Original) The method of claim 1, wherein the first electrode or the second electrode has a protruding shape.

4. (Currently Amended) A method of manufacturing a semiconductor device, comprising:

    providing a substrate having a first electrode thereon;

    dispensing a sealing resin to a region of the substrate that does not include the first electrode;

providing a semiconductor chip having a second electrode on a peripheral portion of a front surface of the semiconductor chip;

placing the semiconductor chip over the substrate so that the front surface of the semiconductor chip faces the sealing resin;

applying a negative pressure to a central portion of a back surface of the semiconductor chip and a positive pressure to a peripheral portion of the back surface of the semiconductor chip so that the first and second electrodes come into a contact; and

applying, after the application of the positive pressure to the peripheral portion, a positive pressure to the central portion of the back surface of the semiconductor chip so that the sealing resin extends in a space between the substrate and the front surface of the semiconductor chip.

5. (Original) The method of claim 4, wherein the sealing resin comprises fillers.

6. (Original) The method of claim 4, wherein the first electrode or the second electrode has a protruding shape.

7. (Original) The method of claim 4, wherein the applying of the negative pressure comprises an air suction.